

Overview

The purpose of this notification is to communicate that Xilinx[®] defense-grade product chip-capacitor manufacturer will change the manufacturing location for chip-capacitors used in Xilinx defense-grade “XQ” products.

Description

Xilinx defense-grade product chip-capacitor manufacturer will change its chip-capacitor manufacturing location for various capacitors. Xilinx has worked with the supplier to qualify this capacitor manufacturing location. This change enables Xilinx to better support long-term customer demand. There is no change in the fit, form, function or reliability of the capacitor with this change.

Products Affected

This change affects all speeds, temperature variations of defense-grade “XQ” product grades of Virtex[®]-4, Virtex[®]-5, Virtex[®]-6, Virtex[®]-7, Kintex[®]-7 and Zynq[®]-7000 as defined in the tables below. Any associated specification control document (SCD) versions of the standard part numbers are also affected.

Table 1: Virtex-4Q Device-Packages

Device	Package-Pin
XQ4VLX60	FF1148
XQ4VLX100	
XQ4VLX160	
XQ4VLX80	
XQ4VSX55	

Device	Package-Pin
XQ4VFX60	FF1152
XQ4VFX100	
XQ4VFX60	EF672

Table 2: Virtex-5Q Device-Packages

Device	Package-Pin
XQ5VFX70T	EF665
XQ5VSX50T	
XQ5VLX85	EF676
XQ5VLX110	
XQ5VLX110T	
XQ5VLX155T	EF1136
XQ5VFX70T	
XQ5VFX100T	
XQ5VSX95T	

Device	Package-Pin
XQ5VLX110	EF1153
XQ5VLX220T	EF1738
XQ5VLX330T	
XQ5VFX100T	
XQ5VFX130T	FF1738
XQ5VFX200T	
XQ5VSX240T	

Table 3: Virtex-6Q Device-Packages

Device	Package-Pin
XQ6VLX130T	RF1156
XQ6VLX240T	
XQ6VSX315T	
XQ6VSX475T	
XQ6VLX130T	RF784
XQ6VLX240T	

Device	Package-Pin
XQ6VLX240T	RF1759
XQ6VLX550T	
XQ6VSX315T	
XQ6VSX475T	

Table 4: Virtex-7Q Devices-Packages

Device	Package-Pin
XQ7V585T	RF1157
XQ7VX330T	
XQ7VX690T	
XQ7VX690T	RF1158
XQ7V585T	RF1761
XQ7VX330T	
XQ7VX485T	
XQ7VX690T	
XQ7VX485T	RF1930
XQ7VX690T	
XQ7VX980T	

Table 5: Kintex-7Q and Zynq-7000 Devices-Packages

Device	Package-Pin
XQ7Z030	RB484
XQ7Z100	RF1156
XQ7K325T	RF676
XQ7K410T	
XQ7Z030	
XQ7Z045	RF900
XQ7K325T	
XQ7K410T	
XQ7Z045	
XQ7Z100	

Key Dates and Ordering Information

Xilinx will start manufacturing devices with capacitors from the new capacitor manufacturing location after the PCN-FYI release date.

Qualification Data

Xilinx has worked with the chip-capacitor supplier to perform chip-capacitor level qualification testing. All the necessary qualification data will be available upon request.

Response

No response is required.

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
07/16/2018	1.0	Initial release

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